

**Amendments to the Specification:**

Please replace the paragraph beginning at page 9, line 10, with the following rewritten paragraph:

-- After the flux is applied, die 102 is aligned with and placed onto a placement site on the package substrate 108 such that the die's bumps 110 are aligned and in contact with the pre-solder covered electrical pads (not shown) on substrate 108. The pre-solder covered electrical pads are electrically connected to the electrical traces (not shown) within the substrate. Substrate 108 is typically composed of an organic material, such as PTFE (such as ~~Teflon~~ TEFLON®<sup>TM</sup>, available from Gore, Eau Claire, WI), bismaleimide triazine (BT) resin, and other epoxy. However, substrate 108 may also be composed of ceramic or ceramic-plastic materials. Any conventional method for fabricating substrate 108 may be used. For example, laminate and substantial build-up fabrication methods can be used. Heat, typically above 200°C (e.g., 240°C), is applied to one or more of the die and the package substrate, causing bumps 110 to alloy and form electrical connections between die 102 and package substrate 108. The package is then cooled to harden the connection. Then, where necessary, the remaining flux residue is substantially removed in a cleaning step, for instance by washing with an appropriate solvent.--